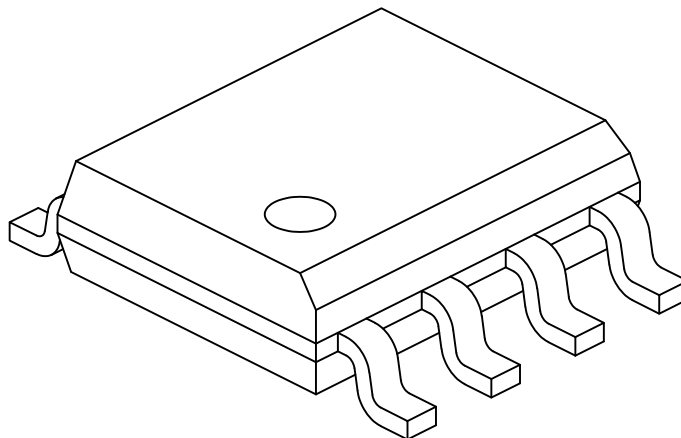


# 8-Lead Plastic Small Outline (C2X) - Narrow, 3.90 mm (.150 In.) Body [SOIC]

## Atmel Legacy Global Package Code SWB

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Pins	N		8		
Pitch	e		1.27 BSC		
Overall Height	A	–	–	1.75	
Molded Package Thickness	A2	1.25	–	–	
Standoff §	A1	0.10	–	0.25	
Overall Width	E		6.00 BSC		
Molded Package Width	E1		3.90 BSC		
Overall Length	D		4.90 BSC		
Chamfer (Optional)	h	0.25	–	0.50	
Foot Length	L	0.40	–	1.27	
Footprint	L1		1.04 REF		
Lead Thickness	c	0.17	–	0.25	
Lead Width	b	0.31	–	0.51	
Lead Bend Radius	R	0.07	–	–	
Lead Bend Radius	R1	0.07	–	–	
Foot Angle	θ	0°	–	8°	
Mold Draft Angle	θ1	5°	–	15°	
Lead Angle	θ2	0°	–	–	

**Notes:**

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
- Dimensioning and tolerancing per ASME Y14.5M  
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.  
 REF: Reference Dimension, usually without tolerance, for information purposes only.
- Datums A & B to be determined at Datum H.